


**PRODUCT / PROCESS CHANGE INFORMATION**

**1. PCI basic data**

1.1 Company		STMicroelectronics International N.V
1.2 PCI No.	AMS/18/10954	
1.3 Title of PCI	New testing flow in subcontractor Carsem Malaysia for selected products in TSSOP slim package	
1.4 Product Category	See product list	
1.5 Issue date	2018-06-18	

**2. PCI Team**

<b>2.1 Contact supplier</b>	
2.1.1 Name	ROBERTSON HEATHER
2.1.2 Phone	+1 8475853058
2.1.3 Email	heather.robertson@st.com
<b>2.2 Change responsibility</b>	
2.2.1 Product Manager	Lorenzo NASO
2.1.2 Marketing Manager	Marcello SAN BIAGIO
2.1.3 Quality Manager	Jean-Marc BUGNARD

**3. Change**

<b>3.1 Category</b>	<b>3.2 Type of change</b>	<b>3.3 Manufacturing Location</b>
Transfer	Line transfer for a full process or process brick (process step, control plan, recipes) from one site to another site: Testing (SOP 2617)	Assembly and Test & Finishing : Carsem Malaysia

**4. Description of change**

	<b>Old</b>	<b>New</b>
<b>4.1 Description</b>	- Assembly : Carsem Malaysia - Testing : Ismeca handler in ST Muar	- Assembly : Carsem Malaysia - Testing : Pentamaster handler in Carsem Malaysia
<b>4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?</b>	No impact	

**5. Reason / motivation for change**

<b>5.1 Motivation</b>	This new testing flow will reduce our cycle time on this package and therefore improve our customers delivery support
<b>5.2 Customer Benefit</b>	SERVICE IMPROVEMENT

**6. Marking of parts / traceability of change**

<b>6.1 Description</b>	New finished good codes
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**7. Timing / schedule**

<b>7.1 Date of qualification results</b>	2018-06-12
<b>7.2 Intended start of delivery</b>	2018-07-31
<b>7.3 Qualification sample available?</b>	Upon Request

**8. Qualification / Validation**

<b>8.1 Description</b>			
<b>8.2 Qualification report and qualification results</b>	In progress	<b>Issue Date</b>	

9. Attachments (additional documentations)
10954 Public product.pdf

10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
LM258AST	LM258AST	
LM358AST	LM358AST	
	LM358AWST	
	LMV822AIST	
TS1852AIST	TS1852AIST	
TS1872AIST	TS1872AIST	
TS419IST	TS419IST	
	TSV358AIST	
	TSV522AIST	
	TSV522IST	
	TSV612AIST	
	TSV6192AIST	
	TSV6192IST	
	TSV622AIST	
	TSV622IST	
	TSV6292AIST	
	TSV6292IST	
	TSV632AIST	
	TSV632IST	
	TSV6392AIST	
	TSV6392IST	
	TSV992AIST	
	TSX562AIST	
	TSX562IST	
	TSX632AIST	

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